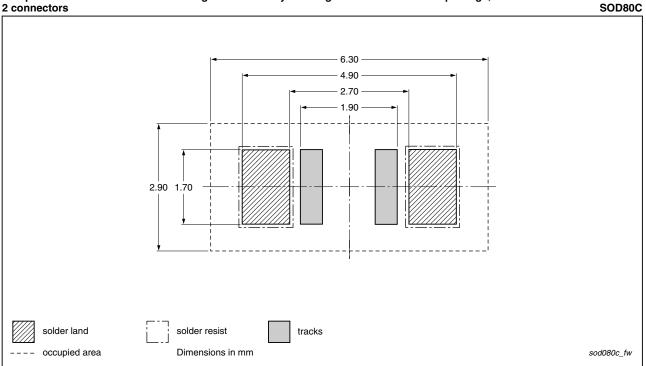


Wave soldering footprint



Footprint information for wave soldering of hermetically sealed glass surface-mounted package;

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